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DSCF001

Silicon NPN epitaxial planar type

For general amplification

Marking Symbol : C1

Package Code : ML3-N4-B

Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	60	V
Collector-emitter voltage (Base open)	VCEO	50	V
Emitter-base voltage (Collector open)	VEBO	7	V
Collector current	IC	100	mA
Peak collector current	ICp	200	mA
Collector power dissipation	Pc	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Pin name	1.	Base
	2.	Emitter
	3.	Collector

Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 µA, IE = 0	60			V
Collector-emitter voltage (Base open)	VCEO	IC = 2 mA, IB = 0	50			V
Emitter-base voltage (Collector open)	VEBO	IE = 10 µA, IC = 0	7			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 20 V, IE = 0			0.1	µA
Collector-emitter cutoff current (Base open)	ICEO	VCE = 10 V, IB = 0			100	µA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 2mA	210		460	-
Collector-emitter saturation voltage	VCE(sat)	IC = 100 mA, IB = 10 mA		0.13	0.3	V
Transition frequency	fT	VCE = 10 V, IC = 2 mA		150		MHz
Collector output capacitance (Common base, input open circuited)	Cob	VCB = 10 V, IE = 0, f = 1 MHz		1.5		pF

Note: Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

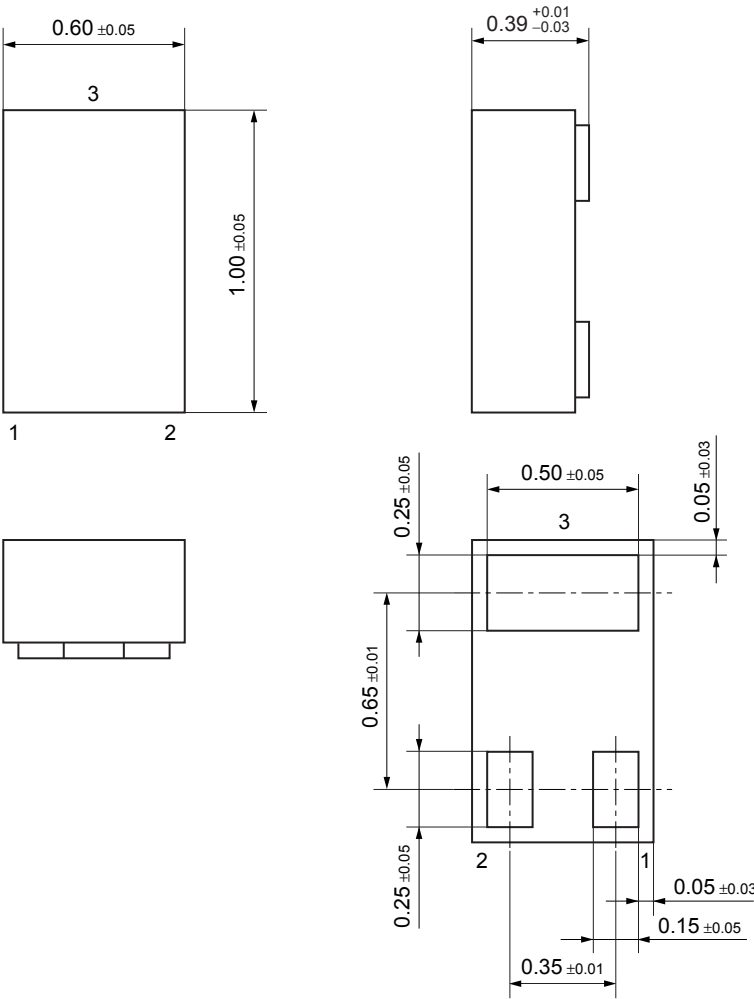
Packing

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel

2010.2.26	2010.7.27	
Prepared	Revised	

ML3-N4-B

Unit: mm



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